Celanese
The chemistry inside innovation™

HOSTAFORM® MT®8R02

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Hostaform® MT®8R02 is an improved wear performance grade targeted at injection molding grade with a molecular weight for excellent moldability and optimum properties in demanding applications.

Hostaform® MT®8R02 is a special grade developed for medical industry applications and complies with:

- CFR 21 (177.2470) of the Food and Drug Administration (FDA) and is listed in the Drug Master File (DMF 11559) and the Device Master File (MAF 1079)
- the corresponding EU and national registry regulatory requirements
- biocompatibility in tests corresponding to USP <88> Class VI/ISO 10993
- low residual monomers
- no animal-derived constituents

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	8.5	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	

Typical mechanical properties

Tensile modulus	2700	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	62	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	30	%	ISO 527-1/-2
Charpy notched impact strength, 23°C	8	kJ/m^2	ISO 179/1eA
Poisson's ratio	0.38[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	82	°C	ISO 75-1/-2

Physical/Other properties

Density	1400	kg/m^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C

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Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	134	°C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low wear / Low friction

Additional information

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling, drying may be necessary to prevent splay and odor problems.

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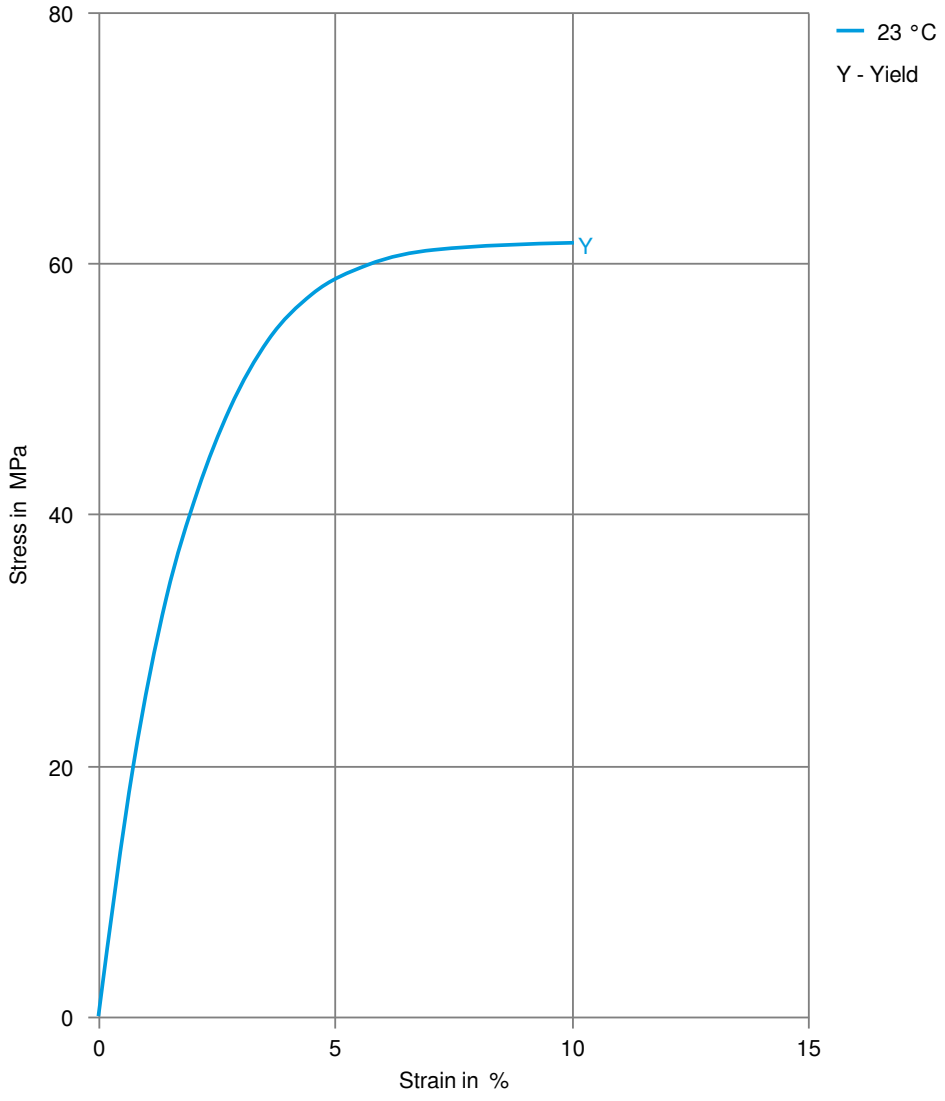
Stress-strain



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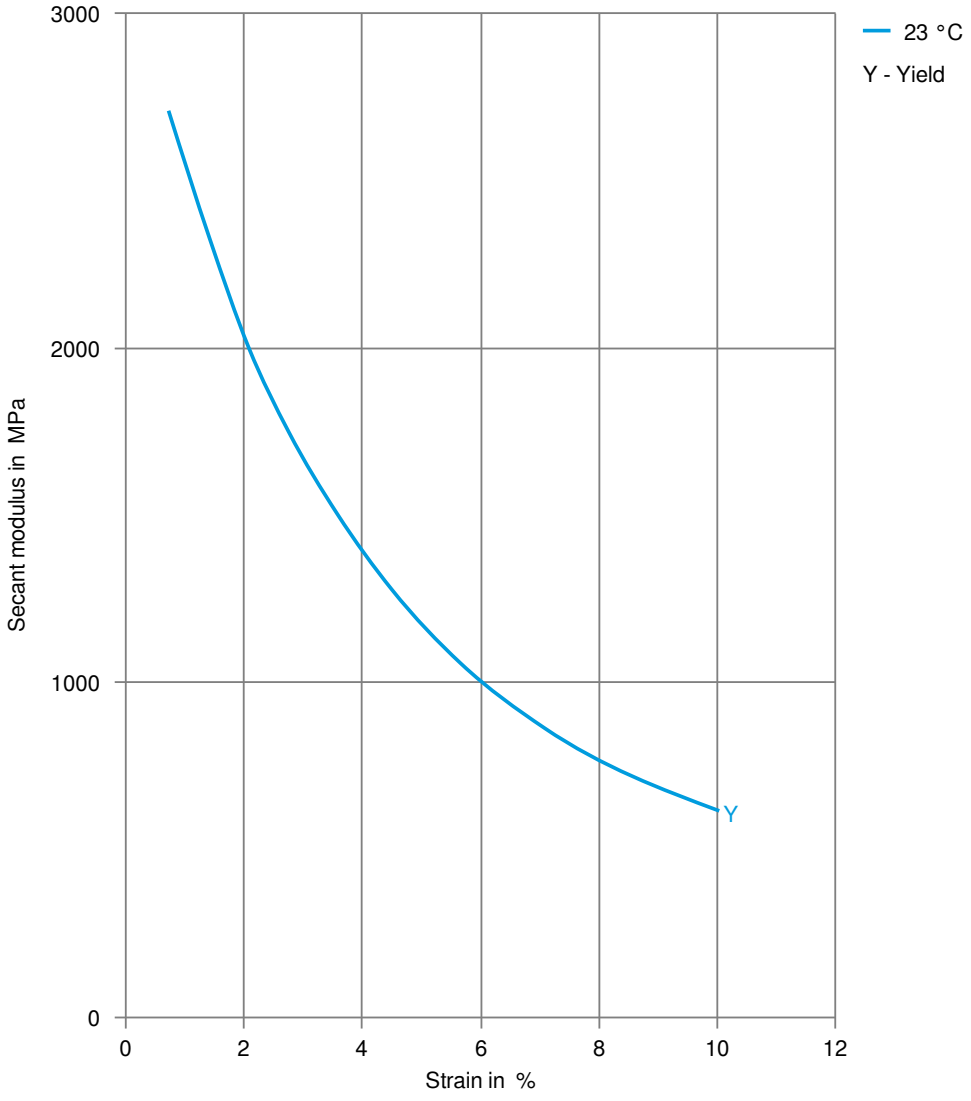
Secant modulus-strain



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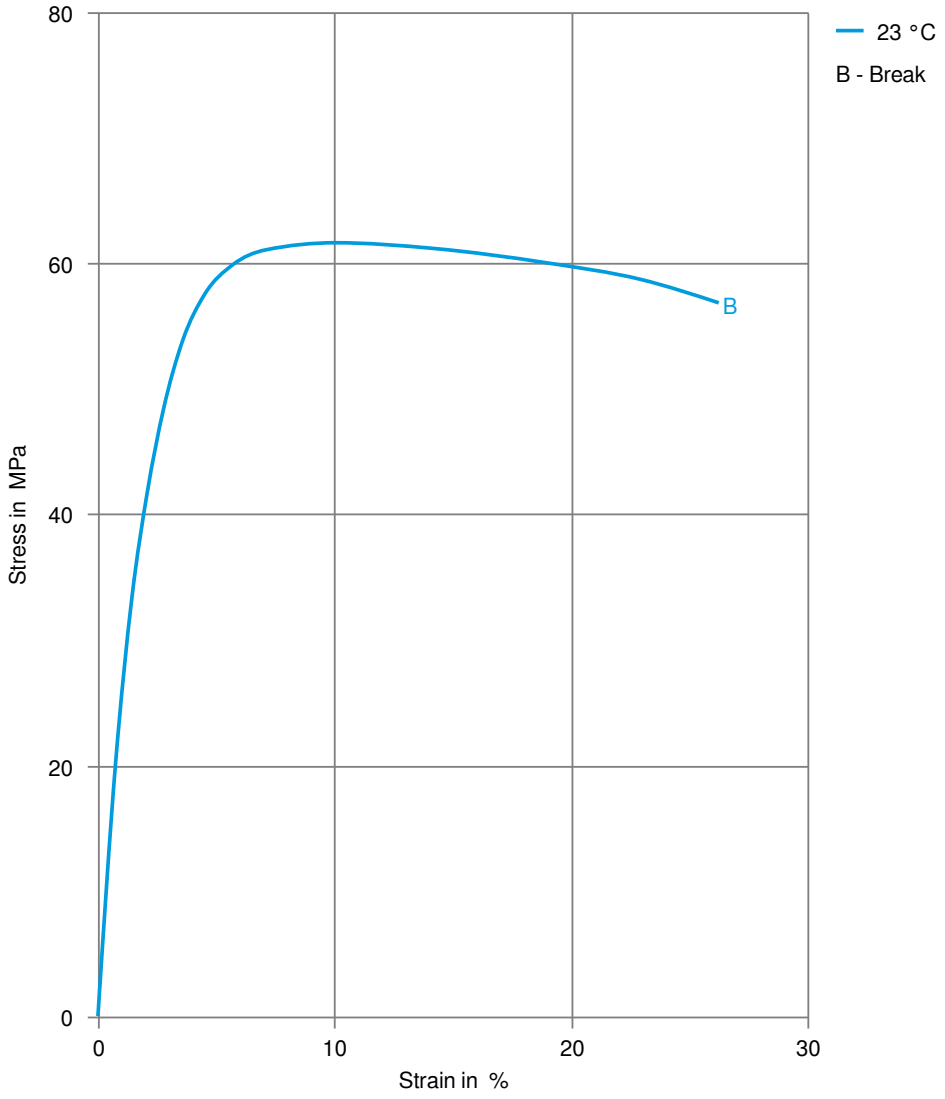
Stress-strain, 50mm/min



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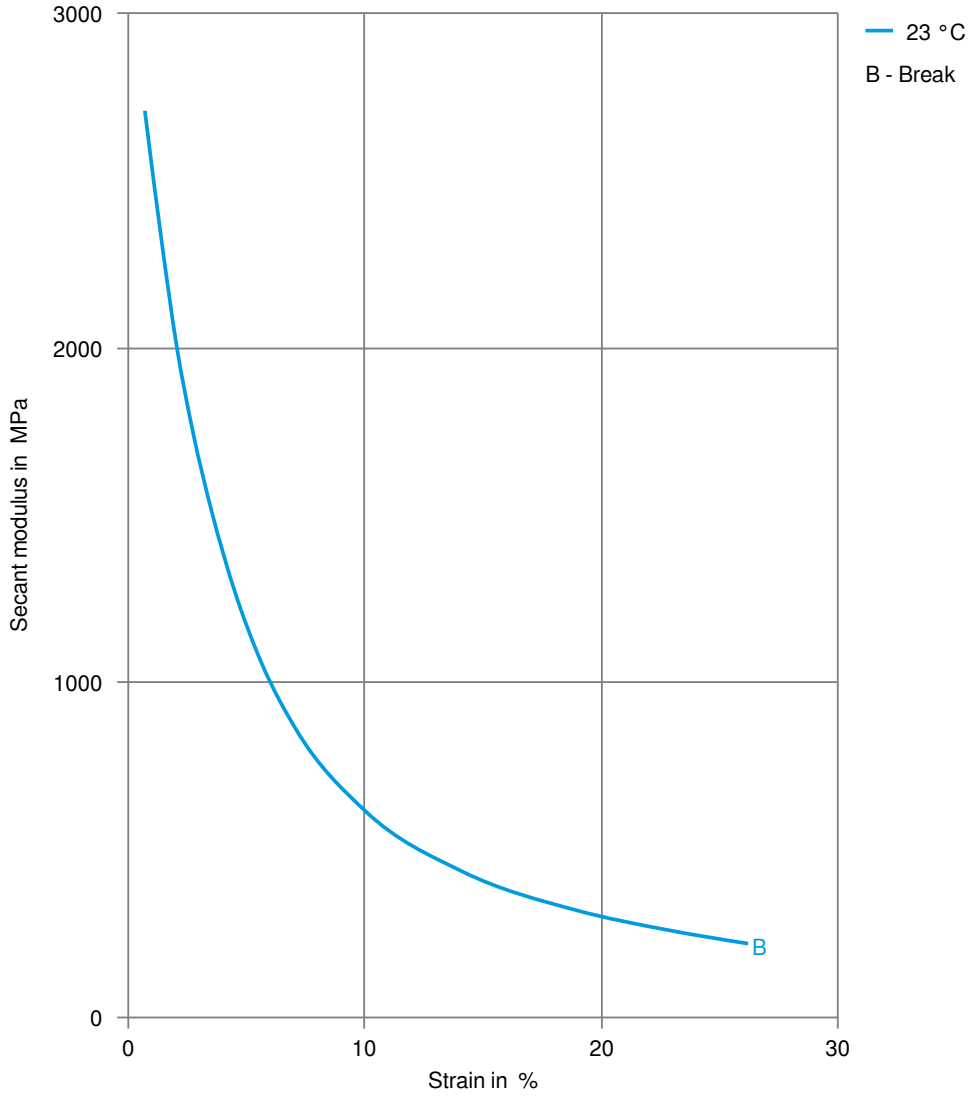
Secant modulus-strain, 50mm/min



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